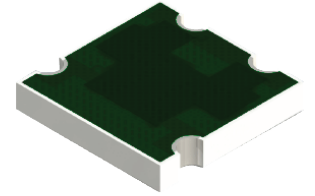


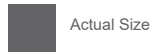
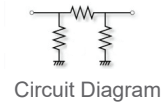
ATC2525ZZ-XXXXJN-99 Features:

- PI Configuration
- Solderable Terminals
- Customer Defined Testing Available
- Symmetrical Design*
- Tape & Reel or Waffle Pack Available (Standard is bulk)



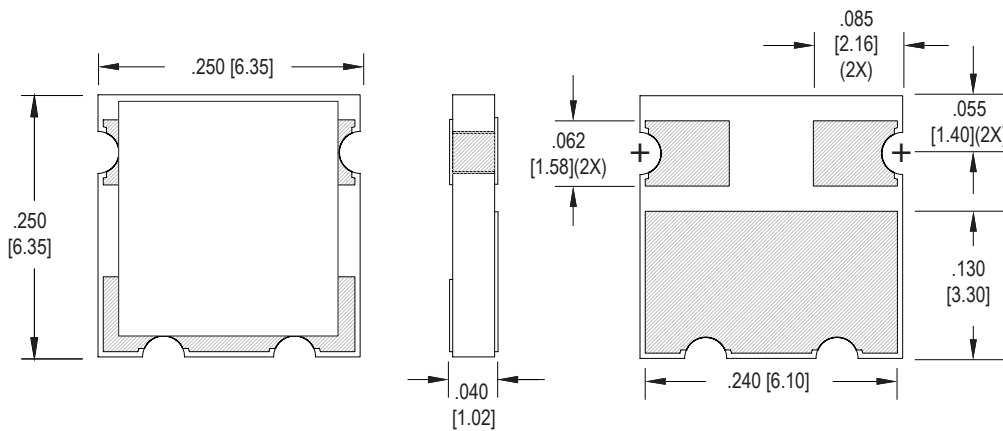
ATC2525ZZ-XXXXJN-99 Parameters:

Nominal Attenuation Range:	1dB - 10dB
Operating Frequency:	DC - 2GHz**
Attenuation Tolerance:	-0.3dB, +0.35dB (1 - 3dB) -0.4dB, +0.6dB (4 - 10dB)
Rated Power:	See page 2
Return Loss (Typical)**:	16dB or Better
Impedance:	50Ω
Construction:	Thick Film on BeO
Operating Temperature:	-55 to +150°C

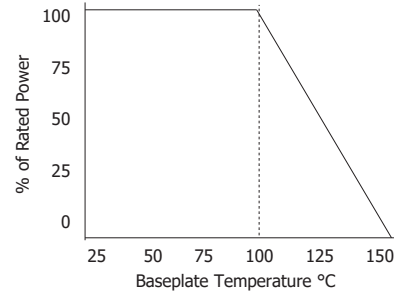


* Can be mounted in either direction
** In a matched, continuous 50Ω system with proper workmanship

ATC2525ZZ-XXXXJN-99 Dimensions:



ATC2525ZZ-XXXXJN-99 Power Derating Curve



Ordering Information:

ATC	2525	ZZ	-	XXXX	JN	-	99	UU
Prefix for 3 Sided Wraparound Attenuator w/ Castellations					Normal Inspection Contact factory for additional options		Substrate 99 - 0.040" BeO	Packaging Blank - Bulk TR - Tape and Reel WP - Waffle Pack
Size 2525				Value Code Examples 0100 - 1dB 0500 - 5dB 0200 - 2dB 1000 - 10dB				
Terminal Metallization				RoHS	Magnetic	Solder	Epoxy	Wirebond
CB - SnPb over Nickel over Silver				No	Yes	Yes	No	No
CT - Matte Tin over Nickel over Silver				Yes	Yes	Yes	No	No

Barry Industries reserves the right to change part number and/or process without notification.

ATC2525ZZ-XXXXJN-99 Power Ratings:

Attenuation (dB)	Input Power (W)	Baseplate-film Thermal Resistance (250°C max film temperature)	R In to Out (part ID only)
1	127	1.15°C/W	5.75Ω
2	73	2.05	11.46
3	54	2.73	17.10
4	46	3.22	22.63
5	42	3.55	28.01
6	39	3.75	33.23
7	37	4.01	38.25
8	33	4.51	43.05
9	30	4.99	47.62
10	27	5.44	51.95

ATC2525ZZ-XXXXJN-99 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65°C to +150°C 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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